

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Hiroshi Ono</td> <td>07/07/2011</td> </tr> <tr> <td>Takashi Shinoda</td> <td>07/07/2011</td> </tr> <tr> <td>Yuuhei Okada</td> <td>07/13/2011</td> </tr> </tbody> </table>		Name	Execution Date	Hiroshi Ono	07/07/2011	Takashi Shinoda	07/07/2011	Yuuhei Okada	07/13/2011		
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<table border="1"> <tr> <td>Name:</td> <td>Hitachi Chemical Company, Ltd.</td> </tr> <tr> <td>Street Address:</td> <td>1-1, Nishi-Shinjuku 2-chome, Shinjuku-ku</td> </tr> <tr> <td>City:</td> <td>Tokyo</td> </tr> <tr> <td>State/Country:</td> <td>JAPAN</td> </tr> <tr> <td>Postal Code:</td> <td>163-0449</td> </tr> </table>		Name:	Hitachi Chemical Company, Ltd.	Street Address:	1-1, Nishi-Shinjuku 2-chome, Shinjuku-ku	City:	Tokyo	State/Country:	JAPAN	Postal Code:	163-0449
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PROPERTY NUMBERS Total: 1											
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CORRESPONDENCE DATA											
<p>Fax Number: (202)822-1111</p> <p>Phone: (202) 822-1100</p> <p>Email: patentmail@whda.com</p> <p><i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i></p> <p>Correspondent Name: Westerman, Hattori, Daniels & Adrian, LL</p> <p>Address Line 1: 1250 Connecticut Ave., NW</p> <p>Address Line 2: Suite 700</p> <p>Address Line 4: Washington, DISTRICT OF COLUMBIA 20036</p>											
ATTORNEY DOCKET NUMBER:	111004A										
NAME OF SUBMITTER:	Stephen G. Adrian										
<p>Total Attachments: 1</p> <p>source=Assignment#page1.tif</p>											

OP \$40.00 13412893

ASSIGNMENT

Whereas, I/we,

NameAddress1) **Hiroshi ONO**

c/o HITACHI CHEMICAL COMPANY, LTD.,

13-1, Higashi-cho 4-chome,
Hitachi-shi, Ibaraki 317-8555 Japan

c/o HITACHI CHEMICAL COMPANY, LTD.,

2) **Takashi SHINODA**13-1, Higashi-cho 4-chome,
Hitachi-shi, Ibaraki 317-8555 Japan

c/o HITACHI CHEMICAL COMPANY, LTD.,

3) **Yuuhei OKADA**13-1, Higashi-cho 4-chome,
Hitachi-shi, Ibaraki 317-8555 Japan

hereinafter called assignor(s), have invented certain improvements in

POLISHING AGENT FOR COPPER POLISHING AND POLISHING METHOD USING SAME

and executed an application for Letters Patent of the United States of America therefor on even date herewith unless otherwise indicated below:

filed on _____, Serial No. _____; and

Whereas

HITACHI CHEMICAL COMPANY, LTD.1-1, Nishi-Shinjuku 2-chome,
Shinjuku-ku, Tokyo 163-0449 Japan

(assignee), desires to acquire the entire right, title and interest in the application and invention, and to any United States patents to be obtained therefor;

NOW THEREFORE, be it known that, for good and valuable consideration from assignee, the receipt of which is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, MY/OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

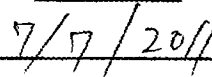
AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with assignee, its successors and assigns, any facts known to ME/US respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

INVENTORSDATE SIGNED

1):

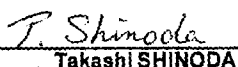
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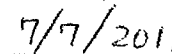

 Hiroshi ONO


 7/7/2011

2):

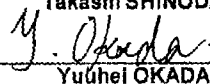
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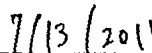

 Takashi SHINODA


 7/7/2011

3):

Name:


 Yuuhei OKADA


 7/13/2011

(Legalization not required for recording but is prima facie evidence of execution under 35 U.S.C. § 261)